COMPONENT SPECIFICATION

M40 SERIES CONNECTORS

AUGUST 2012

CONTENTS:

SECTION	TITLE	PAGE
1	Description of Connector and Intended Application	2
2	Marking of Connector and/or Package	2
3	Ratings	2
Appendix A	Test Methods and Performance – M40-310/320	4
Appendix B	Test Methods and Performance – M40-600/620	7

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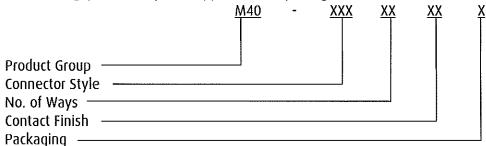
M40 SERIES CONNECTORS

1. DESCRIPTION OF CONNECTOR AND INTENDED APPLICATION.

A selection of 1.00mm pitch connectors, comprising vertical board to board surface mount plugs and sockets.

2. MARKING OF THE CONNECTOR AND/OR PACKAGE (ORDER CODE).

The marking (order code) shall appear on the package and shall be of the following style:



Connector Style:

No. of Ways, Finish & Packaging: See individual drawings

3. RATINGS.

3.1. MATERIAL & FINISH.

Materials:

Mouldings:

M40-310/320	Glass-Filled PA6T, UL94V-0
M40-600/620	
	Phosphor Bronze
Retainer	Brass
Finish:	

3.2. ENVIRONMENTAL CHARACTERISTICS.

Temperature Range:

M40-310/320	-40°C to +105°C
M40-600/620	-20°C to +125°C

3. RATINGS (continued).

3.3.	ELECTRICAL CHARACTERISTICS.	
	Current Rating:	
	M40-310	1.0A AC/DC
	M40-320	1.0A AC/DC
	M40-600/620	0.5A AC/DC
	Voltage Rating:	
	Contact Resistance (initial):	
	M40-310/320	20 mΩ max
	M40-600/620	
	Contact Resistance (after conditioning):	
	M40-310/320	30 mΩ max
	M40-600/620	75 mΩ max
	Dielectric Withstanding Voltage:	
	M40-310/320	.500V AC for 1 minute
	M40-600/620	
	Insulation resistance:	
	M40-310/320	1,000 MΩ min
	M40-600/620	
	•	
3.4.	MECHANICAL CHARACTERISTICS.	
<i>5.</i>	Contact Retention in moulding:	
	M40-320	1 47N min
	M40-600	
	M40-620	
	Mil VEV	
	Retainer retention in moulding:	
	M40-600/620	7 8N min
	1110 000 020 11111111111111111111111111	
	Soldered retainer retention on PC Board:	
	M40-600/620	29.4N min
	·	
	Insertion force (per contact):	
	M40-310/320	1.5N max
	M40-600/620	
	·	
	Withdrawal force (per contact):	
	M40-310/320	0.1N min
	M40-600/620	
	·	
	Durability	
	M40-310/320	300 cycles
	M40-600/620	
		•

<u>COMPONENT SPECIFICATION</u> <u>M40 SERIES CONNECTORS (continued)</u>

APPENDIX A - TEST METHODS AND PERFORMANCE - M40-310/320.

A1.1. TEST CONDITIONS.

Unless otherwise specified, all tests and measurements shall be performed under the conditions and in accordance with EIA 364.

A1.2. TEST METHODS.

A1.2.1. Electrical.

i) Contact Resistance.

Test Method EIA 364-23

Solder a plug and a socket to PC Boards and mate them together. Measure the contact resistance between the two mated boards. Apply the low-level condition of 20mV max. for the open circuit voltage and 100mA max. for the closed circuit current. Contact resistance must not exceed the values stated in section 3.3.

ii) Dielectric Withstanding Voltage.

Mate a plug and socket together (not soldered to a PC Board). Apply between neighbouring contacts a 500V AC current for 1 minute in accordance with EIA 364-20. No creeping discharge, flash-over or insulator break-down is allowed. Current leakage must be less than 0.5mA.

iii) Insulation Resistance.

Mate a plug and socket together (not soldered to a PC Board). Apply between neighbouring contacts a 500V DC voltage for 1 minute. Measurement is taken in accordance with EIA 364-21. Insulation resistance must not be less than the value stated in section 3.3.

A1.2.2. Mechanical.

i) Contact Retention Force.

Test MethodEIA 364-29

Place a connector on a push-on/pull-off machine. Apply force onto the contact head and push the contact in the direction opposite to insertion. Measure the force when the contact dislodges from the moulding. Contact retention must conform to the figure stated in section 3.4.

ii) Insertion/Withdrawal Force.

Test Method EIA 364-13

Place a mated connector pair on a push-on/pull-off machine. Repeat insertion and withdrawal for 30 cycles, at a speed of 50mm/min. along the mating axis. Insertion and withdrawal forces before, during and after the test must conform to those stated in section 3.4.

iii) Durability.

Place a mated connector pair on a push-on/pull-off machine. Repeat insertion and withdrawal for 300 cycles, at a speed of 200 cycles per hour, along the mating axis. Contact resistance before and after the test must meet the values stated in section 3.3.

	MANCE - M40-310/320 (continued).
TEST METHODS (continued).	
A1.2.3. Environmental.	
i) Solderability	
•	EIA-364-52 Category 3
Steam Aging Temperature	90 to 96°C
Steam Aging Duration	8 Hours ±5 min
Soldering Temperature	7/5°C +5°C
	4 to 5 seconds
Result: More than 95% of the surface must have co	
ii) Vibration.	
	EIA-364-28, Condition V, Test letter A
Test Condition	
	50 – 2000Hz
Directions	Three mutually perpendicular direction
	15 minutes / ax
Contact resistance before and after testing must m	neet the values specified in section 3.3. No
electrical discontinuity greater than 1µs must occur	
chipping, breakage or other detrimental damage n	
Wave form Peak acceleration Shock Duration Directions	r during testing. Looseness amongst parts,
	nost not occur.
iv) Humidity.	
	EIA-364-31, Method III, Test Condition
	25°C to 65°C
	90% to 95% RF
Duration	96 Hours
Contact resistance before and after the test must r be no evidence of damage.	neet the values stated in section 3.3. There mu
\ Th Ch .	
v) Thermal Shock.	
•	EIA 364-32. Test Conditio
Test Method	
Test Method Temperature	5° EIA 364-32, Test Conditio 55°C to +85°C
Test Method	55°C to +85°C 5 30 Minutes

be no evidence of damage.

APPENDIX A - TEST METHODS AND PERFORMANCE - M40-310/320 (continued).

APPENDIX A - TEST METHODS AND PERFORMA	ANCE – M40-310/320 (continued).
A1.2. TEST METHODS (continued).	
A1.2.3. Environmental (continued).	
vi) Salt Spray.	
, , , , , , , , , , , , , , , , , , , ,	EIA364-26, Test Condition A
Temperature	
Humidity	
PH Value	65 to 72
Duration	
Contact resistance before and after the test must me	eet the values stated in section 3.3. There must
be no evidence of damage.	
vii) Heat Resistant.	
	EIA-364-17, Test Condition 3, Method A
Temperature	85°C +7°C
Duration	
Contact resistance before and after the test must me	eet the values stated in section 3.3. There must
be no evidence of damage.	The state of the s
viii) Resistance to Soldering Heat	
	EIA-364-56, Procedure 3, Test Condition C
Temperature	
Time	
Contact resistance before and after the test must me	
be no evidence of damage. Mechanical performance	
stated in section 3.4.	
IR Reflow Temperature profile	220°C, 225°C, 230°C, 240°C, 265°C
Speed	
At 217°C, the connector needs to stay in the IR	
At 260°C, the connector needs to stay in the If	Reflow oven for 5 seconds min.
Contact resistance before and after the test must me	eet the values stated in section 3.3. There must
be no evidence of damage. Mechanical performance	e before and after the test must meet the values

stated in section 3.4.

M40 SERIES CONNECTORS

APPENDIX B - TEST METHODS AND PERFORMANCE - M40-600/620.

B1.1. TEST CONDITIONS.

Unless otherwise specified, all tests and measurements shall be performed under the following conditions in accordance with EIA-364 Standards:

Temperature	15°C to 35°C
Humidity	
Atmospheric pressure	

B1.2. TEST METHODS.

B1.2.1. Electrical.

i) Contact Resistance.

Solder a plug and a socket to PC Boards and mate them together. Measure the contact resistance using the 4-terminal method as shown in Figure 1. Apply 10mV DC max. at a current of 10mA in accordance with EIA-364-06B. for the closed circuit current. Contact resistance must not exceed the values stated in section 3.3.

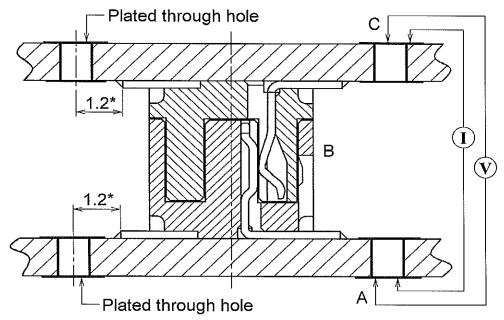


Figure 1: Contact Resistance

Note: Contact resistance is defined as R_{ABC} , i.e. the electrical resistance from point A on the back face of the lower PCB, through contact point B, to point C on the back face of the upper PCB. * = 2.7mm on the next line.

ii) Dielectric Withstanding Voltage.

Mate a plug and socket together (not soldered to a PC Board). Apply between neighbouring contacts a 250V AC rms current for 1 minute in accordance with EIA-364-20B. No creeping discharge, flashover or insulator break-down is allowed.

iii) Insulation Resistance.

Mate a plug and socket together (not soldered to a PC Board). Apply between neighbouring contacts a 100V DC voltage. Measurement is taken in accordance with EIA-364-21C. Insulation resistance must not be less than the value stated in section 3.3.

APPENDIX B - TEST METHODS AND PERFORMANCE - M40-600/620 (continued).	
B1.2. TEST METHODS (continued). <u>B1.2.2. Environmental.</u> i) Heat Resistant.	
Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to the following environment:	
Temperature+80° ±3°C Duration500 ±12 hours	
Contact resistance before and after the test must meet the values stated in section 3.3.	
ii) Cold Resistant. Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to	
the following environment: Temperature30° ±3°C	
Duration500 ±12 hours	
Contact resistance before and after the test must meet the values stated in section 3.3.	
iii) Thermal Shock. Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to the following environment:	
Temperature30° (30 min.) Normal temp. (5 min.) +70°C (30 min.) Normal temp. (5 min.)	
Transition time	
Contact resistance before and after the test must meet the values stated in section 3.3. Detrimental damage affecting the performance must not occur.	
iv) Humidity.	
Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to the following environment in accordance with MIL-STD-202, Method 103 Condition B: Temperature	
Contact resistance before and after the test must meet the values stated in section 3.3.	
v) Salt Spray.	
Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to	
the following environment in accordance with MIL-STD-202, Method 101 Condition B:	
Temperature	
Salt water density	

damage affecting the performance must not occur.

Duration.......48 hours Contact resistance before and after the test must meet the values stated in section 3.3. Detrimental

APPENDIX B - TEST METHODS AND PERFORMANCE - M40-600/620 (continued).

B1.2. TEST METHODS (continued).

B1.2.2. Environmental (continued).

vi) Gas.

Solder a plug and a socket to PC Boards and mate them together. Expose the mated connectors to the following environment:

Chamber temperature	25° ±2°C
Gas	
Duration	

Contact resistance before and after the test must meet the values stated in section 3.3. Detrimental damage affecting the performance must not occur.

vii) Vibration.

Solder a plug and a socket to PC Boards and mate them together. Place the mated connectors on a vibrator machine, and apply the following vibration in accordance with EIA-364-28D. Care should be taken to fix the boards firmly to the vibrator machine to avoid any unnecessary resonance of the boards. During the testing, run a 100mA DC current to check for any electrical discontinuity. The test cycle must cover the following parameters:

- b) Directions......Three mutually perpendicular directions
- d) Sweep duration......Two hours for each direction, totalling 6 hours. Contact resistance before and after testing must meet the values specified in section 3.3. No

electrical discontinuity greater than 10µs must occur during testing. Looseness amongst parts, chipping, breakage or other detrimental damage must not occur.

viii) Shock.

Solder a plug and a socket to PC Boards and mate them together. Place the mated connectors on a shock machine, and apply the following shock in accordance with EIA-364-27B. Care should be taken to fix the boards firmly to the shock machine to avoid any unnecessary resonance of the boards. During the testing, run a 100mA DC current to check for any electrical discontinuity. The test cycle must cover the following parameters:

- a) Maximum shock......50g (490m/s²)
- c) Wave form......Half-sinusoidal

No electrical discontinuity greater than 10µs must occur during testing. Looseness amongst parts, chipping, breakage or other detrimental damage must not occur.

ix) Solderability.

Dip the solder tine of a plug and socket connector in a flux of RMA or R type for 5 to 10 seconds. Then dip the tine into a solder bath (210° C $\pm 5^{\circ}$ C) for 5 ± 0.5 seconds. This test is in accordance with MIL-STD-202, Method 208. More than 90% of the dipped surface must be evenly wet.

APPENDIX B - TEST METHODS AND PERFORMANCE - M40-600/620 (continued).

B1.2. TEST METHODS (continued).

B1.2.2. Environmental (continued).

x) Soldering Heat Resistance (Surface Mount).

Reflow solder 235° ±5°C

220°C min. within 20 seconds 240°C max. within 5 seconds

Detrimental damage affecting the performance of the connector must not occur.

xi) Soldering Heat Resistance (Hand-soldered).

Hand-solder a plug and a socket connector to a PC Board, using a temperature of 350°C for no more than 3 seconds. Detrimental damage affecting the performance of the connector must not occur.

B1.2.3. Mechanical.

i) Contact Retention Force.

Place a connector on a push-on/pull-off machine. Apply force onto the contact head and push the contact in the direction opposite to insertion, at a speed of 25 ±3mm/min. Measure the force when the contact dislodges from the moulding. Plug and socket contact retention must conform to the figures stated in section 3.4.

ii) Retainer Retention Force.

Place a connector on a push-on/pull-off machine. Apply force onto the retainer in the direction opposite to insertion, at a speed of 25 ±3mm/min. Measure the force when the retainer dislodges from the connector. Retainer retention must conform to the figure stated in section 3.4.

iii) Soldered Retainer Retention Force.

Solder a connector to a PC Board, using only the retainers. Place the board onto a push-on/pull-off machine. Pull the connector at a speed of 25 ±3mm/min. Measure the force when the retainer breaks away from the board. Soldered retainer retention must conform to the figure stated in section 3.4.

iv) Repeated Insertion/Withdrawal Force.

Solder a plug and a socket to PC Boards. Place the boards onto a push-on/pull-off machine. Repeat insertion and withdrawal for 30 cycles, at a speed of 25 ±3mm/min. along the mating axis. Insertion and withdrawal forces before, during and after the test must conform to those stated in section 3.4.

v) Electrical Continuity Durability.

Solder a plug and a socket to PC Boards. Place the boards onto a push-on/pull-off machine. Repeat insertion and withdrawal for 30 cycles, at a speed of 25 ±3mm/min. along the mating axis. Contact resistance before and after the test must meet the values stated in section 3.3.